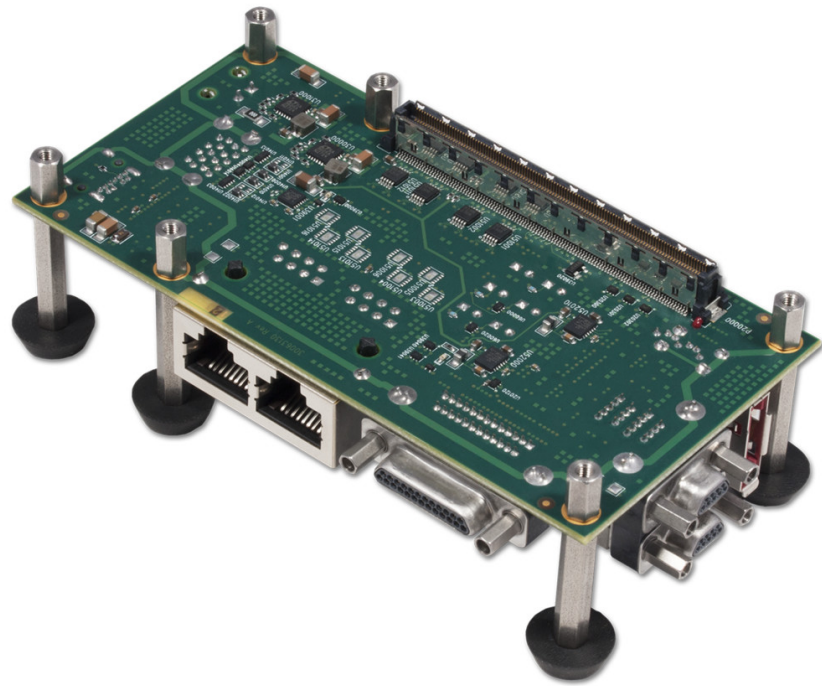


XTend7103

COM Express® Carrier for COM Express® Type 10 Mezzanine Modules

- ▶ Single COM Express® site with AB connector
- ▶ Supports Type 10 COM Express® modules
- ▶ 12 V power supply connector
- ▶ Supports XPedite8150 and XPedite8152 COM Express® modules from X-ES
- ▶ Small Form Factor (SFF) design matches the outline of the XPedite8152



XTend7103

The XTend7103 is a COM Express® carrier card designed to provide a low-cost and compact platform for the XPedite8150 and XPedite8152 COM Express® Type 10 mezzanine modules. The XTend7103, in conjunction with a standard off-the-shelf 12 V power supply, provides a complete desktop or benchtop COM Express platform for development, evaluation, and deployment.

The XTend7103 provides I/O breakout for most of the interfaces on the XPedite8150 and XPedite8152 mezzanine modules. Serial, USB 3.0/2.0, Mini DisplayPort, dual Ethernet, and eSATA connectors are included. In addition, an expansion I/O connector provides I²C, SPI, GPIO, and control signal access.

X-ES

Extreme Engineering Solutions

...Always Fast

Extreme Engineering Solutions

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 Phone: 608.833.1155 • Fax: 608.827.6171
 sales@xes-inc.com • <https://www.xes-inc.com>

COM Express® I/O

- Two Ethernet ports
- One USB 2.0 port
- One USB 3.0 port
- Two RS-232/422/485 serial ports
- One Mini DisplayPort interface
- Expansion I/O connector

Configurability Jumpers

- Write protect
- Boot flash swap
- Independent control of serial port mode and termination

Expansion I/O Connector

- Single micro-DB-25 connector
- SPI
- I²C
- GPIO
- Reset, write protect, and flash swap signals

Power Supplies

- Onboard +5 V, +3.3 V for USB, DisplayPort, and serial transceivers
- Single 12 V input

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1
- Conformal coating available as an ordering option
- Extended ruggedization options may be available, please contact factory

Power Requirements (From 12 V Supply)

- Please consult factory.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g ² /Hz (maximum), 5 to 2000 Hz	0.04 g ² /Hz (maximum), 5 to 2000 Hz	0.1 g ² /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

